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(54) **DEVICES, SYSTEMS, AND METHODS FOR MAKING AND USING CIRCUIT ASSEMBLIES HAVING PATTERNS OF DEFORMABLE CONDUCTIVE MATERIAL FORMED THEREIN**

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(57) **ABSTRACT**

Devices, systems, and methods for making and using circuit assemblies having a pattern of deformable conductive material formed therein are disclosed herein. In various aspects, a circuit assembly can include a substrate layer; a first pattern of deformable conductive material formed on a surface of the substrate layer using a removable stencil; and a first stacked layer configured to cover at least a portion of the first pattern of deformable conductive material.

